

(1.27 mm) .050"

SEAM SERIES

# HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAM](http://www.samtec.com?SEAM)

### Insulator Material:

Black LCP

### Contact Material:

Copper Alloy

### Operating Temp Range:

-55 °C to +125 °C

### Current Rating

(7 mm stack height):

2.7 A per pin

(10 adjacent pins powered)

### Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

### Working Voltage:

240 VAC

### RoHS Compliant:

Yes (-2 Solder type only)

### Lead-Free Solderable:

Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



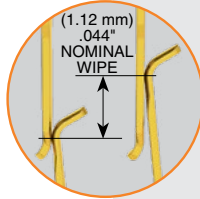
## STANDARDS

- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX
- PISMO™ 2

Visit [www.samtec.com/standards](http://www.samtec.com/standards) for more information.

Mates with:  
SEAF, SEAFP

Standoffs:  
JSO



Low  
insertion/  
extraction  
forces

Up to 500  
Pins



Solder  
charges

## HIGH-SPEED CHANNEL PERFORMANCE

SEAF/SEAM @ 10 mm Mated Stack Height

Rating based on Samtec reference channel.  
For full SI performance data visit [Samtec.com](http://Samtec.com)  
or contact [SIG@samtec.com](mailto:SIG@samtec.com)

PAM 4

56  
G b p s

## OTHER SOLUTIONS

- Up to 560 pins

SEAM ■ NO. PINS PER ROW ■ LEAD STYLE ■ PLATING OPTION ■ NO. OF ROWS ■ SOLDER TYPE ■ A ■ K ■ "X"R

**-10, -15, -20, -30, -40, -50**  
(-10 only available in 04 row)  
(-15 is only available in 4 Row with -02.0 lead style and 10 row with any lead style)

Specify  
LEAD  
STYLE  
from  
chart

**-L**  
= 10 μ" (0.25 μm)  
Gold on contact area,  
Matte Tin on solder tail

**-S**  
= 30 μ" (0.76 μm)  
Gold on contact area,  
Matte Tin on solder tail

**-04**  
=Four Rows  
(-06.5 not available)

**-05**  
=Five Rows  
(-06.5 not available)

**-06**  
=Six Rows  
(-06.5 not available)

**-08**  
=Eight Rows

**-10**  
=Ten Rows

**-1**  
= Tin/Lead Alloy Solder Charge

**-2**  
= Lead-Free Solder Charge

**-A**  
= Alignment Pins  
(Required. Arrays will not self-center on solder pads)

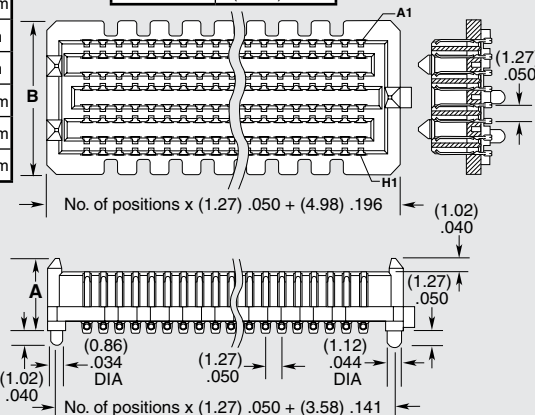
**-K**  
= Polyimide film Pick & Place Pad

**-TR**  
=Tape & Reel

**-FR**  
= Full Reel Tape & Reel Packaging  
(Must order max. quantities per reel. Contact Samtec for parts per reel)

| SEAM LEAD STYLE | MATED HEIGHTS   |         |         |         |
|-----------------|-----------------|---------|---------|---------|
|                 | SEAF LEAD STYLE |         |         |         |
|                 | -05.0           | -06.0   | -06.5   | -07.5   |
| -02.0           | 7 mm            | 8 mm    | 8.5 mm  | 9.5 mm  |
| -03.0           | 8 mm            | 9 mm    | 9.5 mm  | 10.5 mm |
| -03.5           | 8.5 mm          | 9.5 mm  | 10 mm   | 11 mm   |
| -06.5           | 11.5 mm         | 12.5 mm | 13 mm   | 14 mm   |
| -07.0           | 12 mm           | 13 mm   | 13.5 mm | 14.5 mm |
| -09.0           | 14 mm           | 15 mm   | 15.5 mm | 16.5 mm |
| -11.0           | 16 mm           | 17 mm   | 17.5 mm | 18.5 mm |

| NO. OF ROWS | B            |
|-------------|--------------|
| -04         | (7.06) .278  |
| -05, -06    | (9.60) .378  |
| -08         | (12.14) .478 |
| -10         | (14.68) .578 |



| LEAD STYLE | A            |
|------------|--------------|
| -02.0      | (5.61) .221  |
| -03.0      | (6.60) .260  |
| -03.5      | (7.11) .280  |
| -06.5      | (10.16) .400 |
| -07.0      | (10.59) .417 |
| -09.0      | (12.60) .496 |
| -11.0      | (14.61) .575 |

## POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

**Notes:**  
IPC-A-610F & IPC-J-STD-001F Class 3 solder joint.

Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.